BGA Heat Sink (High Aspect Ratio Ext.) Straight Fin





ATS Part#: ATS012012023-SF-2V

Description: 12.00 x 12.00 x 23.00 mm BGA Heat Sink (High Aspect Ratio Ext.) Straight Fin

Heat Sink Type: Straight Fin
Heat Sink Attachment: superGRIP
Equivalent Part Number: N/A

*Image above is for illustration purpose only.

Features & Benefits

- · High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments
- Features a low profile, slant fin array that offers many of the performance benefits of maxiFLOW™ at a great value
- · Higher performance helps ensure reliable product life at a lower cost than other extruded heat sinks
- · Comes standard without interface material or with most common pressure sensitive thermal tapes as a custom option

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	10.21 °C/W	8.4 °C/W	7.3 °C/W	6.7 °C/W	6.2 °C/W	5.8 °C/W	5.5 °C/W
	Ducted Flow	7.4	6.4	5.7	5.3	4.9	4.7	4.5

Product Detail





